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FORM PTO-1594
(Rev. 6-93)



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Patent and
Trademark Office

22390 U.S. PTO
10/860613

060404

Atty Docket #:
ONS00528

102766378

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying part(ies):
Hun Kwang Lee
Ing Hong Ooi
6-4-04
Additional name(s) of conveying party(ies) is provided on attached sheet.

2. Name and address of receiving party(ies):
SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C. of
5005 East McDowell Road, Phoenix, AZ 85008
Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution date of conveyance: March 16, 2004

4. Application number(s) or patent number(s): 10860613
If this document is being filed together with a new application, the execution date of the application is: May 26, 2004

A. Patent Application No.(s):
Additional numbers attached? Yes No

B. Patent No.(s):

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.
Internal Address: Patent Administration - A700
Street Address: P. O. Box 62890
City, State, Zip: Phoenix, Arizona 85082-2890

6. Total number of applications and patents involved:
7. Total fee (37 C.F.R. 3.41).....\$40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number: 501086

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Kevin B. Jackson 38,502 *Kevin B. Jackson* 2 June 2004
Name of Person Signing Reg. No. Signature Date
Total number of pages including cover sheet, attachments, and document: 2

OMB No. 0651-0011 (exp. 4/94)

06/14/2004 METACHE 00000074 501086 10860613

01 FC:8021 40.00 BA

PATENT
REEL: 015444 FRAME: 0160

**ASSIGNMENT OF ENTIRE INTEREST IN INVENTION
BEFORE THE ISSUE OF LETTERS PATENT**

Whereas, the undersigned have invented an invention entitled
**METHOD OF ROUTING AN ELECTRICAL
 CONNECTION ON A SEMICONDUCTOR DEVICE AND STRUCTURE THEREFOR**
(Attorney Docket No. ONS00528)

for which we make application for letters patent in Malaysia; and

Whereas,

SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C., (SCI), a Limited Liability Company of the State of Delaware, United States of America, having a principal place of business at 5005 E. McDowell Road, Phoenix, Arizona 85008, United States of America, is desirous acquiring the said invention and the patent thereto:


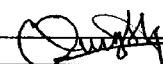

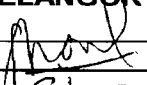
Now, therefore, for valuable consideration receipt of which is hereby acknowledged, we by these presents, do sell, assign, and transfer unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. the full and exclusive right in and to the said invention, as described in the specification executed by us preparatory to obtaining letters patent in Malaysia therefor; said invention, application, and letters patent to be held and enjoyed by the said unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. for its own use and behalf and for its legal representatives, to the full end of the term for which said letters patent may be granted, as fully and entirely as the same would have been held by us had this assignment not been made.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to Malaysia, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters priority of the filing date of the application for Letters Patent of Malaysia under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Patent Office to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI. We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Executed on the date shown next to my/our name below:

	16/03/04		16/03/04
Hun Kwang Lee	Date	Ing Hong Ooi	Date
3, TINGKAT BETEK 2, SG. RAMBAI, PENANG, MALAYSIA 14000		4, JALAN PRIMA 2/8, TAMAN PUCHONG PRIMA, 47100 PUCHONG, SELANGOR D.E. MALAYSIA	
Witnessed by: 	Printed Name: Ghazali Omar	Witnessed by: 	Printed Name: Ghazali Omar
Date: 16/03/04		Date: 16/03/04	